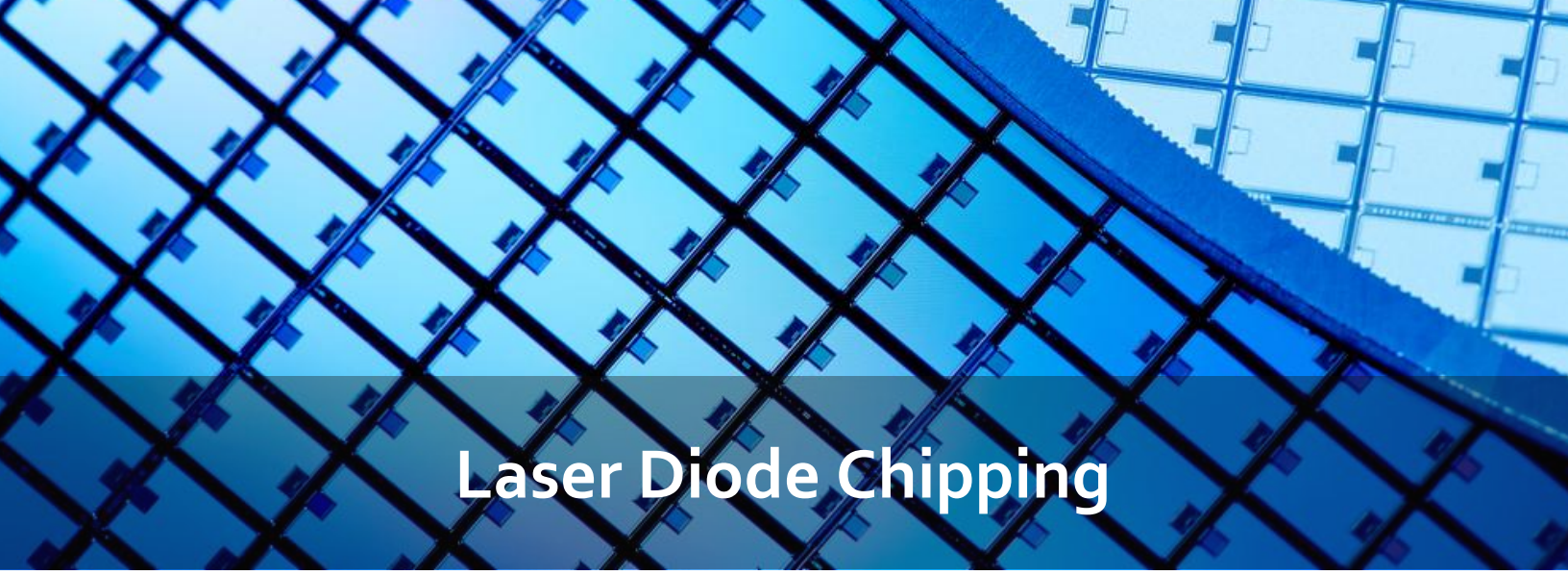


Laser Diode Chipping

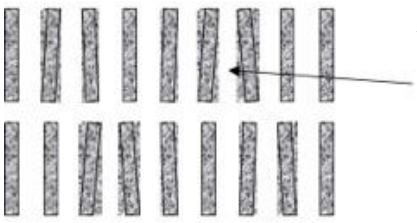
DTX & GSX Scribe & Break Laser Diode Chipping Results in Higher Productivity

- Allows the user to populate the entire work area with laser bars to be processed in a single run.
- Requires only one alignment per bar for both scribe and break, which reduces process time.
- System will completely scribe all laser bars prior to breaking each bar individually.
- Requires minimal operator intervention.
- Prevents the need for multiple load/unload processes.
- Uses less consumable processing materials, such as hoops, protective overlays, and mounting tape.

Background

Processing laser bars can be a laborious and time-consuming process. Prior to the development of this process, the laser bars needed to be aligned individually and processed one at a time. The goal to increase the productivity of laser bar processing has led to the development of this process.

Laser Bar Array



Alignment of laser bars on tape does not require precision placement accuracy. System will compensate for up to 5 degrees of rotation.

DTX & GSX Application Note

dynatex™ INTERNATIONAL